



Data Sheet

Customer: _____

Part No: _____

CL-SP1606UYG-02

Sample No: _____

Description: _____

1606 SMD YellowGreen Color

Item No: _____

| Customer | | | |
|----------|------------|----------|------|
| Check | Inspection | Approval | Date |
| | | | |


Features

- _1.7mmX0.6mm SMT LED, 1.1mm THICKNESS.
- _LOW POWER CONSUMPTION.
- _WIDE VIEWING ANGLE.
- _IDEAL FOR BACKLIGHT AND INDICATOR.
- _VARIOUS COLORS AND LENS TYPES AVAILABLE.
- _PACKAGE: 4000 PCS / REEL.
- _RoHS COMPLIANT.

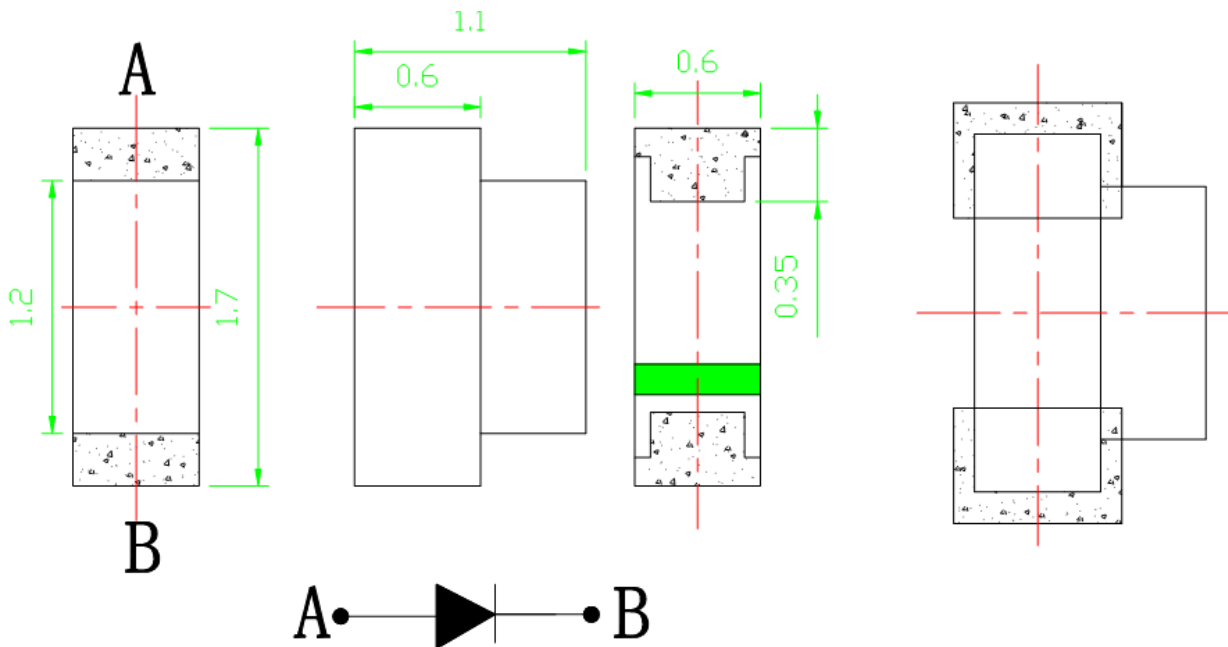
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Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Applications

- 1.Mobile phone Keypad indicator and backlight.
- 2.Flat backlight for LCD, switch and symbol.
- 3.Toys.

Package Dimensions

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

| Part No. | Dice | Lens Type | Iv (mcd) @ 20mA | | Viewing Angle |
|-----------------|--------------|-------------|--------------------|------|------------------|
| | | | Min. | Typ. | 2 θ 1/2 |
| CL-SP1606UYG-02 | Yellow green | WATER CLEAR | 30 | 70 | 120 |

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

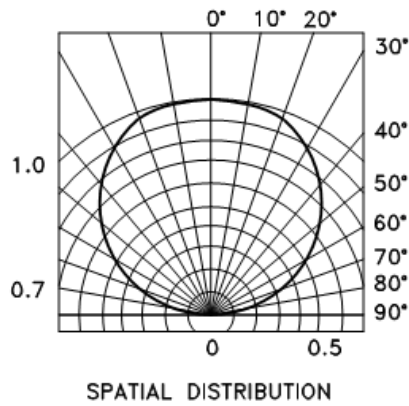
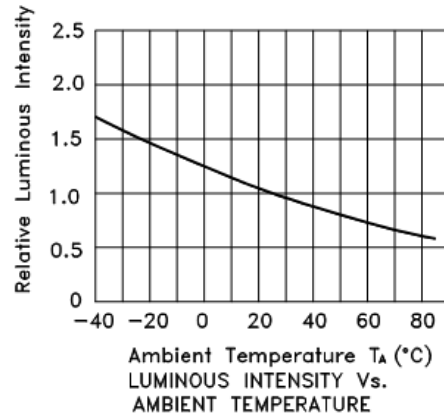
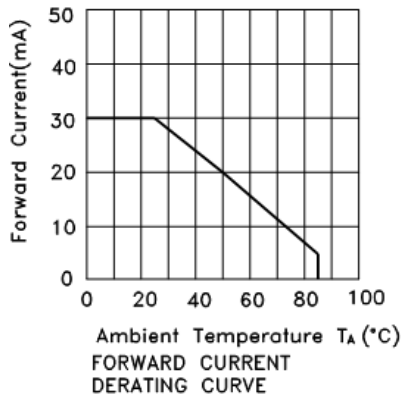
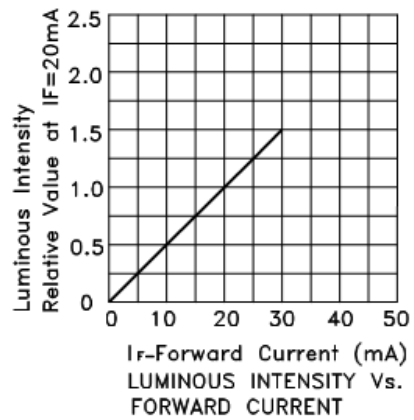
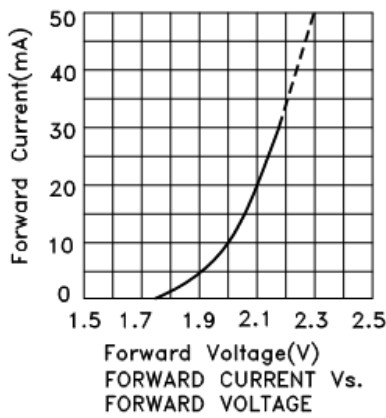
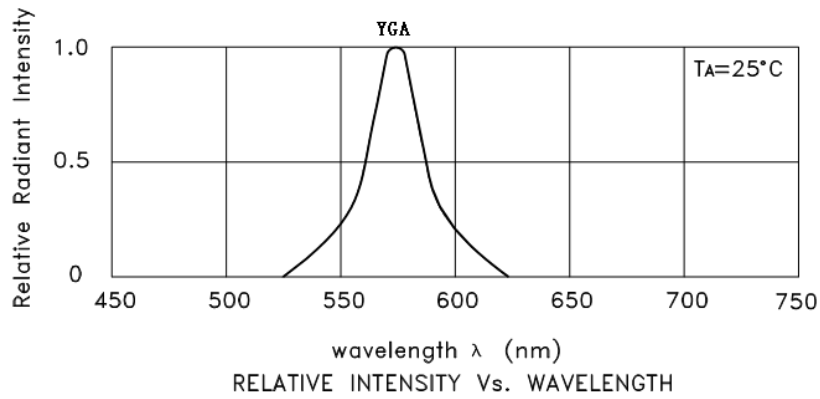
| Symbol | Parameter | Device | Min | Max. | Units | Test Conditions |
|--------|--------------------------|--------------|-----|------|-------|-----------------|
| λD | Dominant Wavelength | Yellow green | 566 | 574 | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Yellow green | 30 | | nm | IF=20mA |
| C | Capacitance | Yellow green | 15 | | pF | VF=0V;f=1MHz |
| VF | Forward Voltage | Yellow green | 1.8 | 2.3 | V | IF=20mA |
| IR | Reverse Current | Yellow green | | 10 | uA | VR = 5V |

Absolute Maximum Ratings at TA=25°C

| Parameter | Yellow green | Units |
|-------------------------------|---------------|-------|
| Power dissipation | 75 | mW |
| DC Forward Current | 25 | mA |
| Peak Forward Current [1] | 80 | mA |
| Reverse Voltage | 5 | V |
| Operating/Storage Temperature | 40°C To +85°C | |

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



RELIABILITY

Test Items and Results

| NO. | Test Item | Reference Standard | Test Condition | (Hours/ Cycles) | Sample | Number of Damaged |
|-----|---|--------------------------|--|--------------------|--------|-------------------|
| 1 | Temperature Cycle | JEITA ED-4701 | -40°C ~ 25°C ~ 100°C ~ 25°C 30 min 5 min 30 min 5 min | 100 Cycles | 50 | 0/50 |
| 2 | Thermal Shock | MIL-STD-202G | -40°C ~ 100°C 15 分钟 15 分钟 | 500 Cycles | 50 | 0/50 |
| 3 | High Temperature Storage | JEITA ED-4701 200 201 | T _a =100°C | 1000 Hours | 50 | 0/50 |
| 4 | Low Temperature Storage | JEITA ED-4701 200 201 | T _a =-40°C | 1000 Hours | 50 | 0/50 |
| 5 | Room Temperature Life Test | | T _a =25±5°C I _F =20mA | 1000 Hours | 50 | 0/50 |
| 6 | High Temperature High Humidity Life Test | | T _a =60°C RH=85% I _F =20mA | 1000 Hours | 50 | 0/50 |
| 7 | Solderability (Reflow Soldering) | JEITA ED-4701 300 303 | T _{sol} =235°C±5°C, 5 sec (Using Flux, Lead Solder) | 1 time, 5 sec | 10 | 0/10 |
| 8 | Resistance to Soldering Heat (Reflow Soldering) | JEITA ED-4701 300 301 | T _{sol} =260°C, 10 sec Pre Treatment: 35°C 95%RH 96 Hrs | 2 time, 10 sec | 10 | 0/10 |

The above test items such as differences or special customer specific requirements according to the actual situation in accordance with the requirements of customers to try the requirements with the customer, the customer is not required by our test standard test. Different products using different current test.

5. Cautions

(1) Soldering Conditions

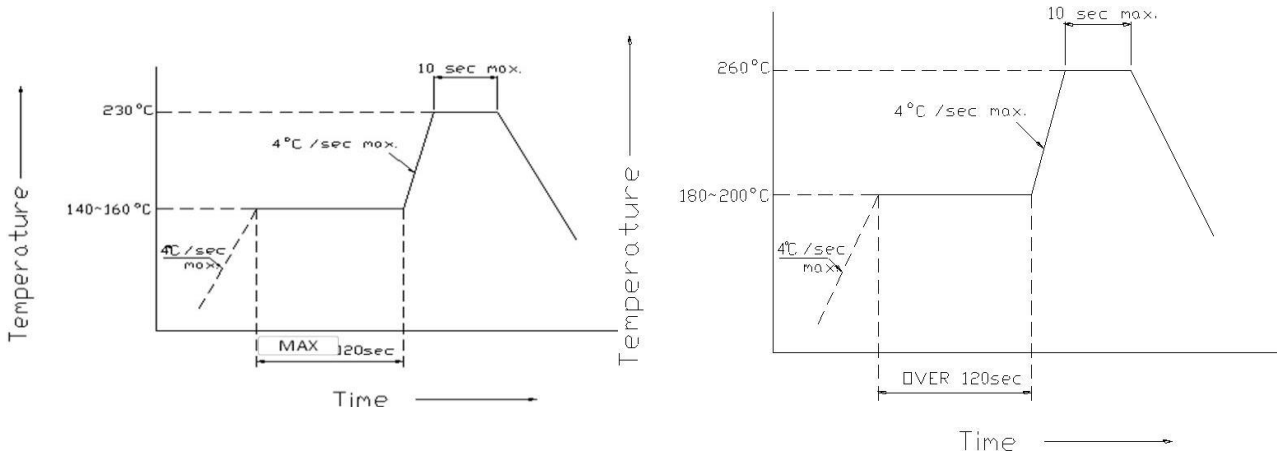
Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and Second soldering process.

(Recommended soldering conditions)

| 回流焊接 Reflow Soldering | | 手工焊接 | |
|-----------------------|-------------------------------|-------------------------------|---|
| 预热温度 Pre-heat | 有铅 Lead Solder | 无铅 Lead-free Solder | 温度 Temperature |
| 预热时间 Pre-heat time | 140 ~ 160° C 120 sec. Max. | 180 ~ 200° C 120 sec. Max. | 焊接时间 Soldering time |
| 峰值温度 Peak temperature | 230° C Max. 10 sec. Max. | 260° C Max. 10 sec. Max. | 350° C Max. 3 sec. Max. (one time only) |
| 焊接时间 Soldering time | 参考下图 | 参考下图 | |
| 条件 Condition | | | |

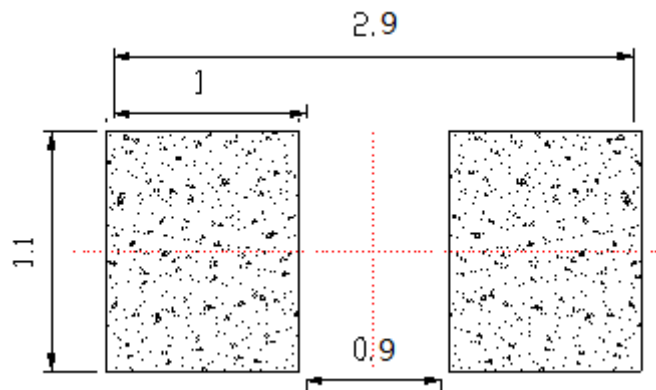
(Lead Solder)

(Lead-Free Solder)



Recommended Soldering Pattern

(Units : mm)



(2) Static Electricity

It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.

All devices, equipment and machinery must be properly grounded.

Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current. Criteria : (VF > 2.0V at IF=0.5mA)

(3) Moisture Proof Package

It is recommended that moisture proof package be used .

(4) Cautions:

4.1. Please check if there is air leak before opening the package, if so, please return the goods back to take drying process for later using.

4.2 Products can be used within 15days after packaging, after that, they must be:

4.2.1 Soldered within 24 hrs

4.2.2 Used in the condition: 30°C within and 60%RH below

4.2.3 Stored in 30%RH for moisture below.

4.3. Products cannot be used for and over 15days after being packaged unless opening the package and take drying our process in 85°C/6H.

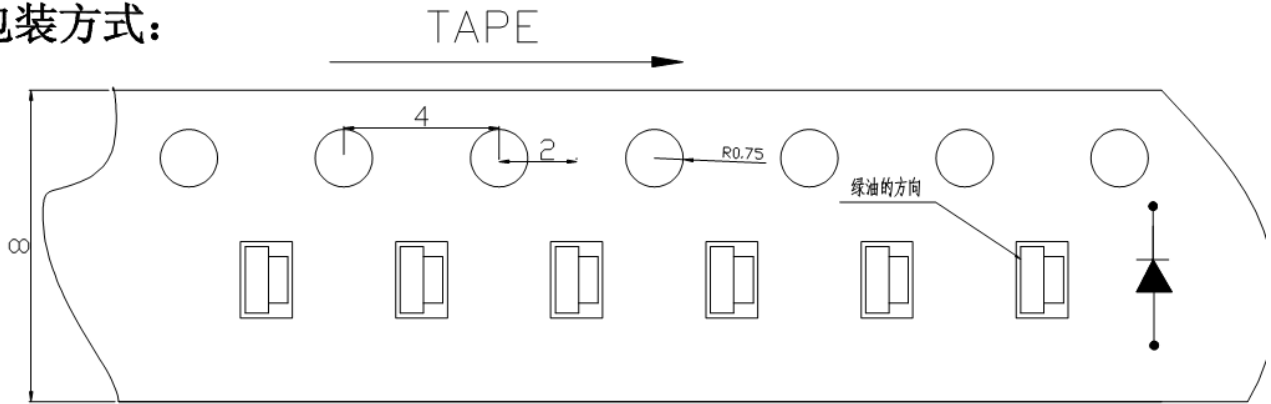
4.4. Products not be used for or over 60days after being packaged please return back to take drying out and packaging process for forward using.

4.5. Products not be used after opening the package need to be dried out for 85°C/6H

PACKAGING

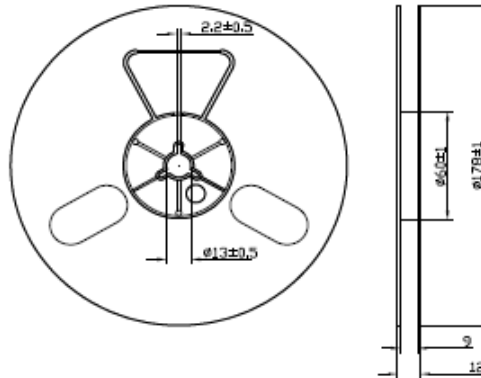
The LEDs are packed in cardboard boxes after taping.

包装方式:

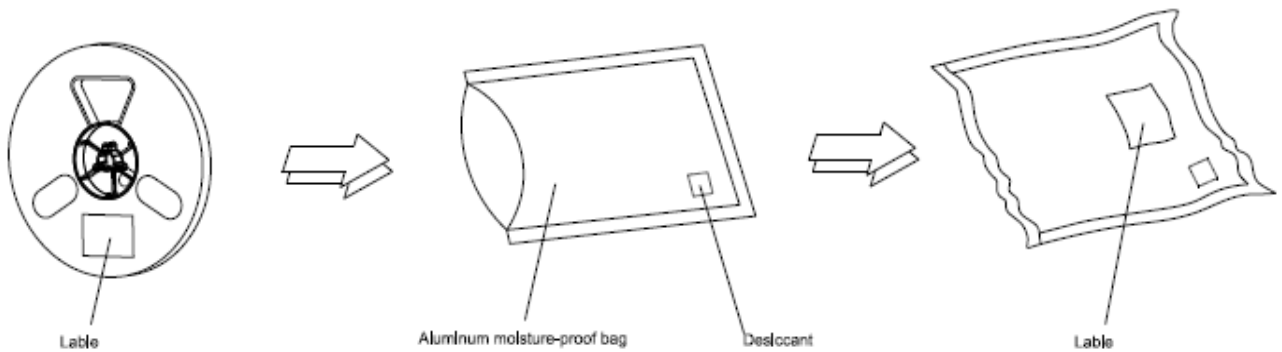


Package: 4000PCS/reel

Reel Dimensions



Moisture Resistant Packaging



Note: The tolerances unless mentioned is ±0.1mm, Unit: mm